Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 5900AF-48G-4XG-2QSFP+ Switch Chassis（JG510A）
HP FF 5700-48G-4XG-2QSFP+ Switch(JG894A)
HP FF 5700-48G-4XG-2QSFP+ TAA Switch(JG895A)
HP FF 5700-40XG-2QSFP+ Switch（JG896A）
HP FF 5700-40XG-2QSFP+ TAA Switch（JG897A)
HP 5900AF-48G-4XG-2QSFP+ TAA Swch（JH038A）
HPE FF 5900 48XG 4Q SFF Switch（JH337A）
HPE FF 5900 48XG 4Q SFF TAA Switch（JH338A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

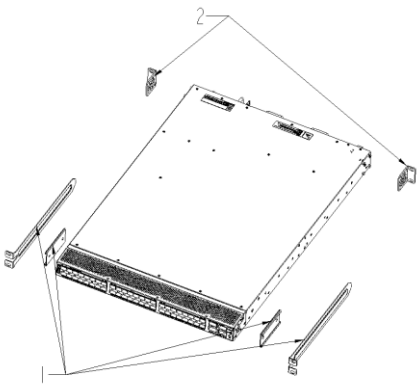
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on mounting angle 2, and then remove mounting angle 2.
3. Unscrew the screws on fan-assembly 3, and then remove fan-assembly 3.
4. Remove the power 4.
5. Remove the filler panel 5.
6. Unscrew the screws on top cover 6, and remove top cover 6.
7. Unscrew the screws on front panel 7, and then remove front panel 7.
8. Unscrew the screws on PCB 9, and remove PCB 9.
9. Unscrew the screws on shielding plate 10, and remove shielding plate 10.
10. Unscrew the screws on PCB 11, and remove PCB 11.
11. Remove all of the labels.
12. Unscrew the screws on 3-2, and then remove 3-2.
13. Unscrew the screws on 3-3, and then remove 3-3.
14. Unscrew the screws on fan 3-4, and then remove fan 3-4.
15. Unscrew the screws on pcb 3-5, and then remove 3-5.
16. Unscrew the screws on pulled handle 3-6, and then remove pulled handle 3-6.
17. Remove shielding finger 3-7.
18. Remove all of the labels.
19. Unscrew the screws on pulled handle 5-1, and then remove pulled handle 5-1.
20. Remove shielding finger 5-3.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.3 Material of the facility built



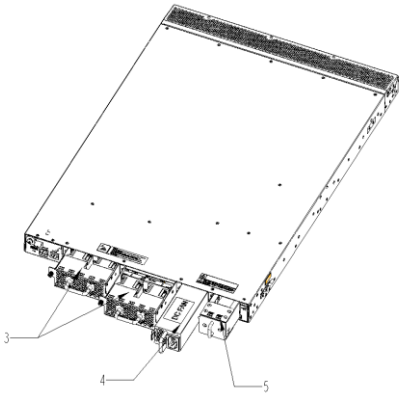
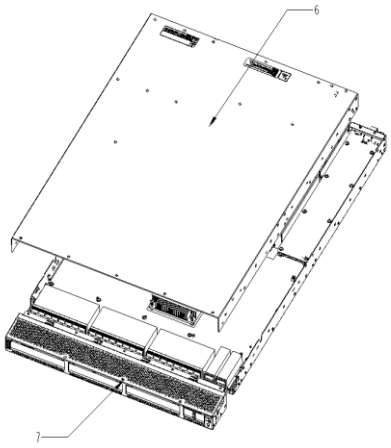


Figure 1Remove mounting angleFigure 2 Rear of HP5900AF-48G-4XG-2QSFP+



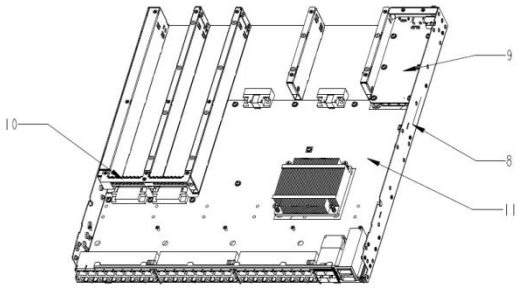
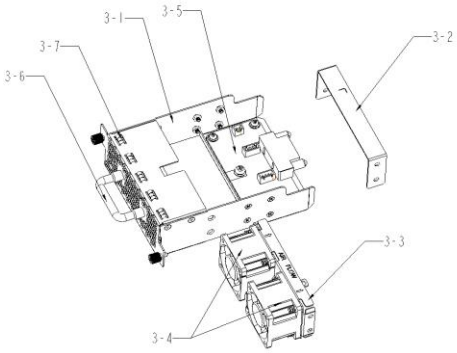


Figure 3Treatments to the productFigure 4Treatments to the product



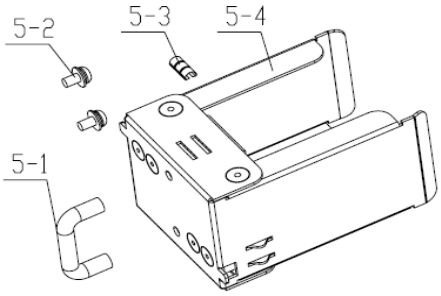


Figure 5 Treatments to fan-assembly 3Figure 6Treatments to filler panel 5

Facility	Components	Material	Weight(g)	Weight	Selective treatment for	Details

				percentage	materials and components	
1		Fe	362	3.76%		Fe recycling
2		Fe	76	0.79%		Fe recycling
3						
	3-1	Fe	170	1.77%		Fe recycling
	3-2	Fe	21	0.22%		Fe recycling
	3-3	Fe	23	0.24%		Fe recycling
	3-4	PC	160	1.66%	Containing brominated flame retardants	
	3-5	Complex PWB	30	0.31%	The surface of PCB is greater than 10 square centimeters;	
	3-6	Fe	1300	13.51%		Fe recycling
	3-7	Be-Cu	34.4	0.36%		Cu recycling
4		Fe	1050	10.91%		Fe recycling
5		Fe	144	1.5%		Fe recycling
6		Fe	1669	17.34%		Fe recycling
7		Fe	360	3.74%		Fe recycling
8		Fe	1862	19.35%		Fe recycling
9		Complex PWB	95	0.99%	The surface of PCB is greater than 10 square centimeters;	
10		Fe	18.3	0.19%		Fe recycling
11		Complex PWB	2250	23.38%	The surface of PCB is greater than 10 square centimeters;	

4. Revised record

Date	Version	Author	Modify content
2014.01.10	V1	Liu Binghui	Add the module JG894A、JG895A、JG896A、JG897A
2014.06.13	V2	Liu Binghui	Add the module JH038A
2015.10.15	V3	Zhou Hongjia	Add the module JH337A、JH338A